

Patent Claims

1. Integrated circuit having at least one microstrip line and at least one port, characterized in that at 5 least some of the ports and/or microstrip lines (1) in the integrated circuit have a removable, reflection-free termination which is integrated on the chip.
2. Integrated circuit according to Claim 1, 10 characterized in that the integrated circuit is in the form of an MMIC circuit.
3. Integrated circuit according to one of the preceding claims, characterized in that the integrated 15 circuit is in the form of a radio-frequency circuit.
4. Integrated circuit according to one of the preceding claims, characterized in that the integrated circuit is in the form of a test circuit. 20
5. Integrated circuit according to one of the preceding claims, characterized in that the ports in the integrated circuit are in the form of coplanar line ports. 25
6. Integrated circuit according to one of the preceding claims, characterized in that the integrated circuit has at least
 - one amplifier and/or
 - one mixer and/or
 - one coupler and/or
 - one power splitter30
7. Integrated circuit according to one of the preceding claims, characterized in that all the ports and/or microstrip lines (1) in the integrated circuit 35

have a removable, reflection-free termination which is integrated on the chip.

8. Integrated circuit according to Claim 6,
5 characterized in that input Lange couplers arranged on a chip have at least one port having a removable, reflection-free termination which is integrated on the chip.

10 9. Integrated circuit according to one of the preceding claims, characterized in that the removable, reflection-free terminations which are integrated on the chip are in the form of absorbing resistors (2).

15 10. Integrated circuit according to one of the preceding claims, characterized in that the removable, reflection-free terminations which are integrated on the chip are arranged symmetrically with respect to radio-frequency signal lines.

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11. Method for manufacturing an integrated circuit, characterized in that an integrated circuit is produced in a first step, with at least some of the ports and/or microstrip lines (1) in the integrated circuit being provided with a removable, reflection-free termination which is integrated on the chip, and in a second step this termination is removed from a prescribable selection of the ports and/or microstrip lines 1 provided with the removable, reflection-free 30 termination which is integrated on the chip.

12. Method according to Claim 11, characterized in that, in the first step of the method according to Claim 11, all the ports and/or microstrip lines (1) in the integrated circuit are provided with a removable, reflection-free termination which is integrated on the chip.

13. Method according to one of Claims 11 or 12, characterized in that absorbing resistors (2) are used for the removable, reflection-free terminations which are integrated on the chip.

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14. Method according to one of Claims 11 to 13, characterized in that the position and dimensions of removable, reflection-free terminations which are integrated on the chip are optimized for a reflection-free termination.

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15. Method according to one of Claims 11 to 14, characterized in that the removable, reflection-free terminations which are integrated on the chip are arranged symmetrically with respect to radio-frequency signal lines.

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16. Method according to one of Claims 11 to 15, characterized in that the removable, reflection-free terminations which are integrated on the chip are removed by a laser.

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17. Method according to one of Claims 11 to 16, characterized in that the ports and/or microstrip lines (1) to be opened are selected in the second step of the method according to Claim 11 on the basis of the requirements of the measurement arrangements used for making contact with the radio-frequency connections.

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18. Method according to one of Claims 11 to 17, characterized in that, following removal of the removable, reflection-free terminations which are integrated on the chip, the ports and/or microstrip lines (1) which are now open in the integrated circuit are connected to a measurement device.

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19. Method according to one of Claims 11 to 18, characterized in that a radio-frequency connection is

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used as the connection to the measurement device.

20. Method according to one of Claims 11 to 19,
characterized in that the measurement device is used to
5 test individual parts of the integrated circuit, such
as amplifiers, mixers, couplers and/or power splitters,
individually on their own.

21. Method according to one of Claims 11 to 20,
10 characterized in that the removal of removable,
reflection-free terminations which are integrated on
the chip stipulates properties of the integrated
circuit.

15 22. Method according to one of Claims 11 to 21,
characterized in that the removal of removable,
reflection-free terminations which are integrated on
the chip stipulates the suppressed sideband of a mixer.